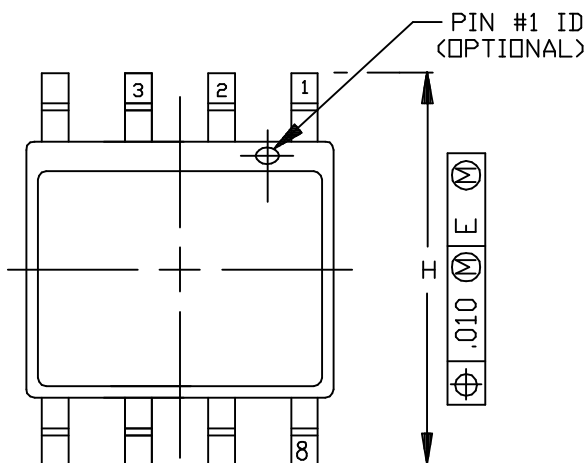
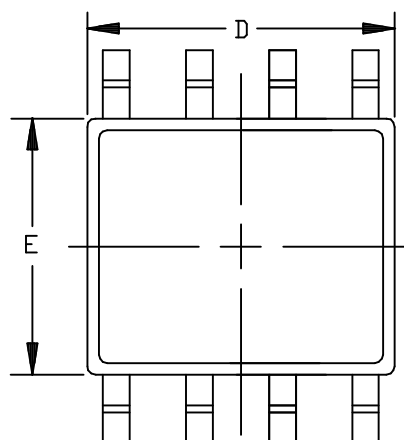


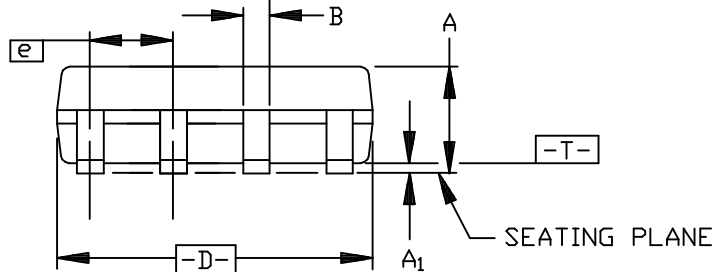
TOP VIEW



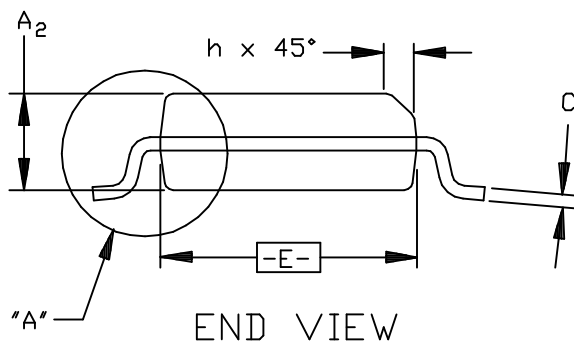
BOTTOM VIEW



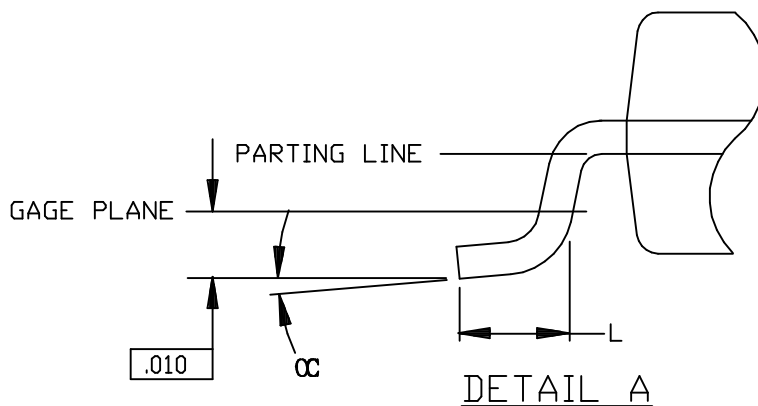
⌀ .010 (M) T E (M) D S



SIDE VIEW



SYMBOL	INCHES		
	MIN.	NOM.	MAX.
A	.059	.064	.068
A ₁	.004	.006	.0098
A ₂	.055	.058	.061
B	.013	.016	.020
C	.0075	.008	.0098
D	.189	.194	.196
E	.150	.155	.157
e	.050 BSC		
H	.229	.236	.244
h	.010	.013	.019
L	.016	.025	.035
α	0°	5°	8°



NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982.
2. DIMENSION "D" DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED .006" PER SIDE.
3. DIMENSION "E" DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED .010" PER SIDE.
4. LEAD FINISH: SOLDER PLATE
5. CONFORMS TO JEDEC MS-012

8 LEAD SOIC (S08)